

MJ N-Channel Enhancement Mode Power MOSFET

Description

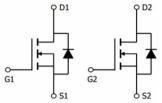
The MJ30ND35Q uses advanced trench technology and design to provide excellent R_{DS(ON)} with low gate charge. It can be used in a wide variety of applications.

General Features

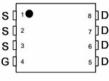
- ♦ Vps=30V.lp=35A $R_{DS(ON)}$ <13m Ω @ V_{GS} =10V $R_{DS(ON)}$ <19m Ω @ Vgs=4.5V
- ♦ High density cell design for ultra low Rdson
- Fully characterized Avalanche voltage and current
- ◆ Good stability and uniformity with high Eas
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Application

- ◆ Power switching application
- Hard Switched and High Frequency Circuits
- ◆ Uninterruptible Power Supply

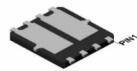












Schematic diagram

Pin Assignment

Top View

Bottom View

100% UIS TESTED! 100% ΔVds TESTED!

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
MJ30ND35Q	MJ30ND35Q	DFN 3.3x3.3-8L	-	-	-

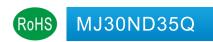
Absolute Maximum Ratings (Tc =25 ℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	VDS	30	V
Gate-Source Voltage	Vgs	±20	V
Drain Current-Continuous	lo	35	А
Drain Current-Continuous(Tc =100°C)	ID(100°C)	24.8	А
Pulsed Drain Current	Ідм	140	А
Maximum Power Dissipation	Po	30	W
Single pulse avalanche energy (Note 5)	Eas	0.24	mJ
Derating factor		72	W/°C
Operating Junction and Storage Temperature Range	Тл,Тѕтс	-55 To 150	°C

Thermal Characteristic

Thermal Resistance, Junction-to-Case (Note 2)	RθJA	4.17	°C/W
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Electrical Characteristics (TA =25°Cunless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics	'	1				
Drain-Source Breakdown Voltage	BVDSS	V _{GS} =0V I _D =250µA	30	_	-	V
Zero Gate Voltage Drain Current	loss	V _{DS} =30V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	lgss	V _{DS} =±20V,V _{DS} =0V	_	-	±100	nA
On Characteristics (Note 3)	1					
Gate Threshold Voltage	VGS(th)	V _{DS} =V _{GS} ,I _D =250µA	0.9	1.3	2.0	V
Drain-Source On-State Resistance		V _{GS} =10V, I _D =20A	-	11	13	mΩ
Brain-Source Off-State Resistance	Rds(on)	V _{GS} =4.5V, I _D =20A	-	14.5	19	mΩ
Forward Transconductance	grs	V _{DS} =5V,I _D =20A	26	-	-	S
Dynamic Characteristics (Note 4)		1				
Input Capacitance	Clss	V _{DS} =15V,V _{GS} =0V, F=1.0MHz	-	1000	-	PF
Output Capacitance	Coss		-	180.8	-	PF
Reverse Transfer Capacitance	Crss		-	164.4	-	PF
Switching Characteristics (Note 4)	,	-				
Turn-on Delay Time	t _{d(on)}		-	5	-	nS
Turn-on Rise Time	tr	VDD=15V, RL=0.75Ω	-	12	-	nS
Turn-Off Delay Time	td(off)	V _{GS} =10V,R _G =3Ω	-	19	-	nS
Turn-Off Fall Time	tf		-	6	-	nS
Total Gate Charge	Qg		_	17	-	nC
Gate-Source Charge	Qgs	V _{DS} =15V,I _D =20A, V _{GS} =10V	_	2.8	-	nC
Gate-Drain Charge	Qgd	-	-	3.9	-	nC
Drain-Source Diode Characteristics	l l	I.		l		
Diode Forward Voltage (Note 3)	VsD	V _{GS} =0V,I _S =-20A	-		1.2	V
Diode Forward Current (Note 2)	Is		_	-	35	А
Reverse Recovery Time	trr	TJ=25°C, IF=20A	-	19		nS
Reverse Recovery Charge	Qrr	di/dt=100A/µs (Note 3)	-	10	_	nC
Forward Turn-On Time	ton	Intrinsic turn-on time is n	egligible(tu	ırn-on is d	ominated b	⊥ oy LS+LC

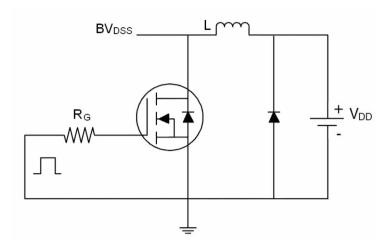
Notes:

- $\textcircled{1} \ \ \mathsf{Repetitive} \ \ \mathsf{Rating:} \ \ \mathsf{Pulse} \ \ \mathsf{width} \ \ \mathsf{limited} \ \ \mathsf{by} \ \ \mathsf{maximum} \ \ \mathsf{junction} \ \ \mathsf{temperature}.$
- ② Surface Mounted on FR4 Board, $t \le 10$ sec.
- 3 Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.
- $\ensuremath{\mathfrak{A}}$ Guaranteed by design, not subject to production

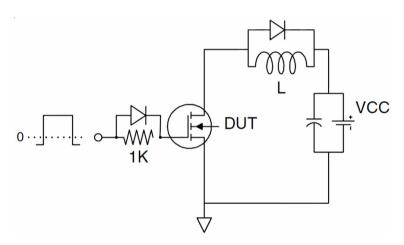




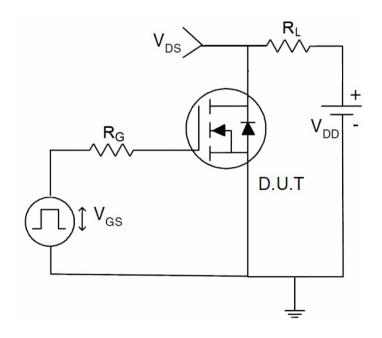
Test circuit



Eas test Circuit



Gate charge test Circuit



Switch Time Test Circuit



Typical Electrical and Thermal Characteristics (Curves)

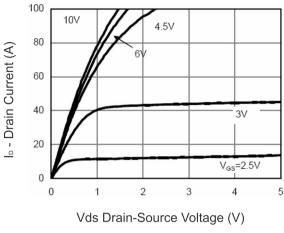
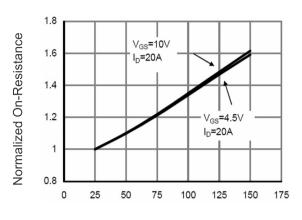


Figure 1 Output Characteristics



T_J -Junction Temperature(°C) Figure 4 Rdson-Junction Temperature

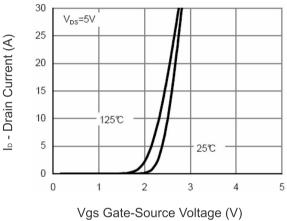


Figure 2 Transfer Characteristics

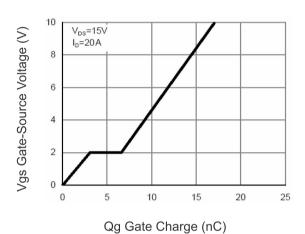


Figure 5 Gate Charge

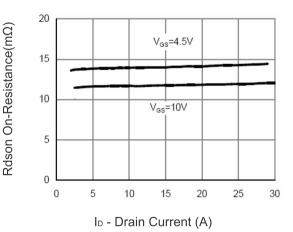


Figure 3 Rdson- Drain Current

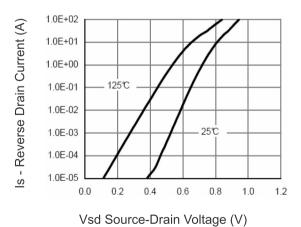


Figure 6 Source- Drain Diode Forward



le - Drain Current (A)



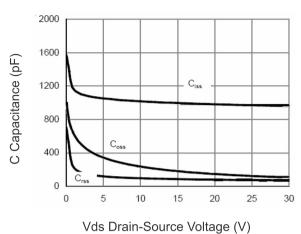
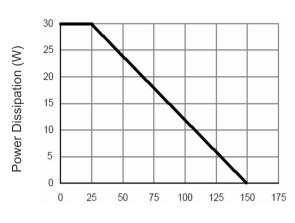


Figure 7 Capacitance vs Vds



T_J -Junction Temperature(°C) Figure 9 Power De-rating

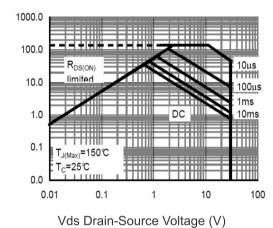
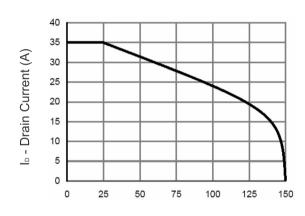
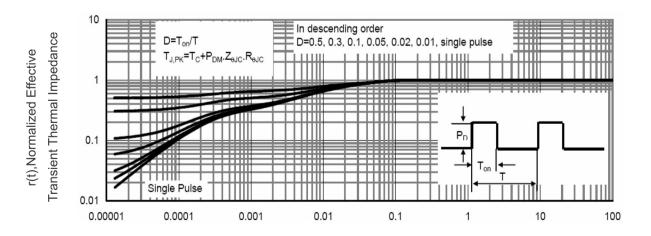


Figure 8 Safe Operation Area



T_J -Junction Temperature(°C)
Figure 10 I_D Current De-rating

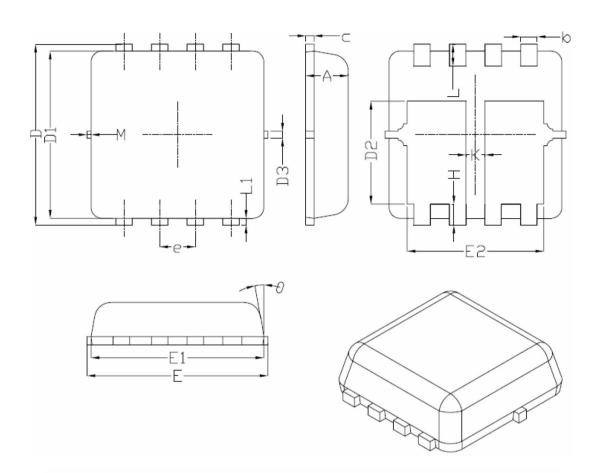


Square Wave Pluse Duration(sec)
Figure 11 Normalized Maximum Transient Thermal Impedance

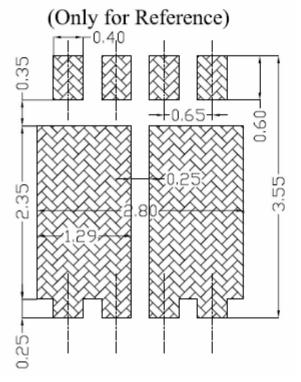




DFN3.3X3.3-8L Package Information

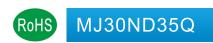


CVI (DOT	DIMENSIONAL REOMTS			
SYMBOL	MIN	NOM	MAX	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
С	0.10	0.15	0.25	
D	3.25	3.35	3.45	
DI	3.00	3.10	3.20	
D2	1.78	1.88	1.98	
D3		0.13		
E	3.20	3.30	3.40	
EI	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
e	0.65BSC			
H	0.30	0.39	0.50	
L	0.30	0.40	0.50	
L1		0.13		
K	0.30		-	
θ		10°	12°	
М	*	*	0.15	



Land Pattern





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